

Applications

- W-CDMA / LTE
- Macrocell Base Station Driver
- Microcell Base Station
- · Small Cell Final Stage
- Active Antenna
- General Purpose Applications

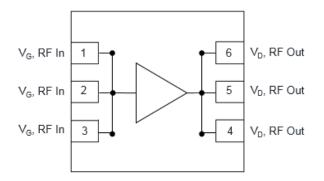


6 Pin 7.2x6.6mm DFN

Product Features

- Operating Frequency Range: DC to 3.6 GHz
- Operating Drain Voltage: 48 V
- Maximum Output Power (PSAT): 82.8 W at 2.6 GHz
- Maximum Drain Efficiency: 78.5% at 2.6 GHz
- Efficiency-Tuned P3dB Gain: 19.4 dB at 2.6 GHz
- Surface Mount Plastic Package

Functional Block Diagram



General Description

The QPD0050 is a wide band over-molded QFN discrete power amplifier. The device is a single stage unmatched power amplifier transistor.

The QPD0050 can be used in Doherty architecture for the final stage of a base station power amplifier for small cell, microcell, and active antenna systems. The QPD0050 can also be used as a driver in a macrocell base station power amplifier.

The wide bandwidth of the QPD0050 makes it suitable for many different applications from DC to 3.6 GHz. QPD0050 can deliver P_{SAT} of 82 W at 48 V operation at 2.6 GHz.

Lead-free and ROHS compliant.

Pin Configuration

Pin No.	Label
1,2,3	RF IN, V _G
4,5,6	RF OUT, V _D
Backside Paddle	RF/DC Ground

Ordering Information

Part No.	ECCN	Description	
QPD0050		75 W 48 V DC-3.6 GHz GaN RF Power Transistor	



Absolute Maximum Ratings

Parameter	Rating
Gate Voltage (V _G)	–10 V
Drain Voltage (V _D)	+55 V
Maximum RF Input Power `	35 dBm
VSWR Mismatch, P1dB Pulse (20% duty cycle, 100 μ width), T = 25°C	10:1
Storage Temperature	−65 to +150 °C

Operation of this device outside the parameter ranges given above may cause permanent damage.

Recommended Operating Conditions

Parameter	Min	Тур	Max	Units
Operating Temperature	-40			°C
Gate Voltage (V _G)		-2.7		V
Drain Voltage (V _D)		48		V
Quiescent Current (Icq)		130		mA
T _{CH} for >10 ⁶ hours MTTF			225	°C

Electrical performance is measured under conditions noted in the electrical specifications table. Specifications are not guaranteed over all recommended operating conditions.

RF Characterization - Power-Tuned Load Pull Performance

Test conditions unless otherwise noted: V_D = 48 V, I_{CQ} = 130 mA, T = 25°C, Pulsed CW (10% duty cycle, 100 μs width)

Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	4.01 – j2.99	6.15 + j1.97	21.04	48.78	63.68
2000	4.47 – j1.53	5.92 + j1.82	20.40	48.53	63.31
2140	6.09 – j1.33	6.11 + j0.96	19.68	48.45	61.46
2200	5.20 – j0.08	5.89 + j0.43	19.05	48.37	58.86
2500	6.86 + j0.57	4.74 – j1.10	17.68	49.04	62.82
2600	7.57 + j0.97	4.74 – j1.09	17.64	49.18	67.65
2700	7.43 + j1.34	4.92 – j2.26	16.84	49.03	61.32
3400	10.25 – j0.25	4.47 – j4.64	15.16	48.04	56.00
3500	9.38 + j0.01	4.47 – j4.63	15.25	48.12	59.38
3600	8.86 + j0.04	4.47 – j4.63	15.89	48.04	57.87

RF Characterization – Efficiency-Tuned Load Pull Performance

Test conditions unless otherwise noted: V_D = 48 V, I_{CQ} = 130 mA, T = 25°C, Pulsed CW (10% duty cycle, 100 μs width)

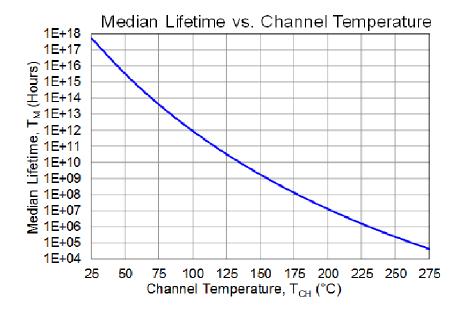
Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	4.01 – j2.99	5.11 + j8.94	23.18	45.85	81.70
2000	4.01 – j1.53	4.80 + j4.73	22.06	47.49	71.76
2140	6.09 – j1.33	4.58 + j5.24	21.68	46.77	74.50
2200	5.20 – j0.08	3.91 + j4.22	21.30	46.91	71.82
2500	6.86 + j0.57	3.25 + j2.36	19.62	47.24	76.03
2600	7.57 + j0.97	2.91 + j1.69	19.36	47.27	78.51
2700	7.43 + j1.34	2.91 + j1.69	19.02	46.87	77.83
3400	10.25 – j0.25	2.17 – j2.02	16.84	46.16	70.07
3500	9.38 + j0.01	1.89 – j2.71	16.17	46.11	70.86
3600	8.86 + j0.04	2.62 – j3.05	17.07	46.98	67.45



Thermal Information				
Parameter	Conditions	Value	Units	
Thermal Resistance at Average Power (0,0)	T _{CASE} = 105°C, T _{CH} = 139.12°C CW: P _{DISS} = 13.43 W, P _{OUT} = 3.55 W	2.54	°C/W	

Notes:

Median Lifetime

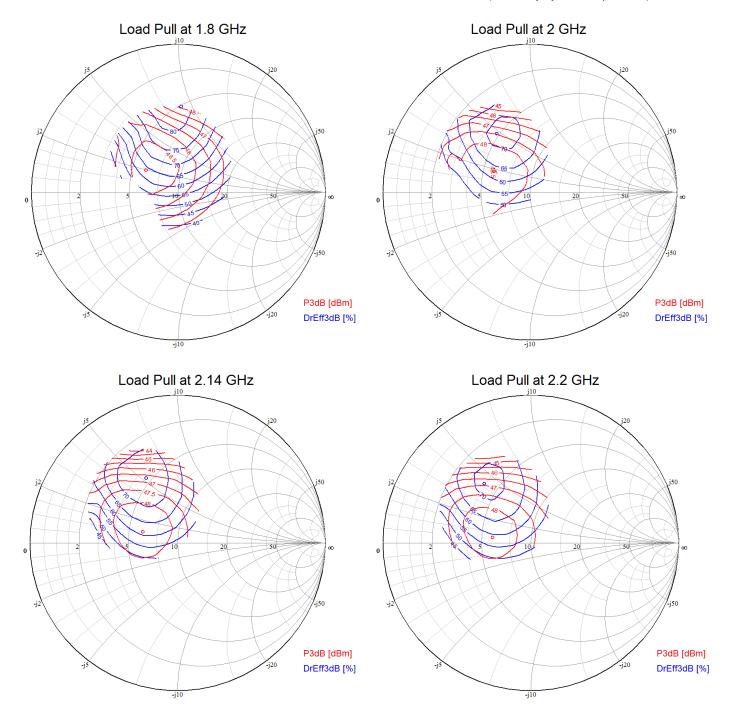


^{1.} Thermal resistance measured to package backside.



Load Pull Plots

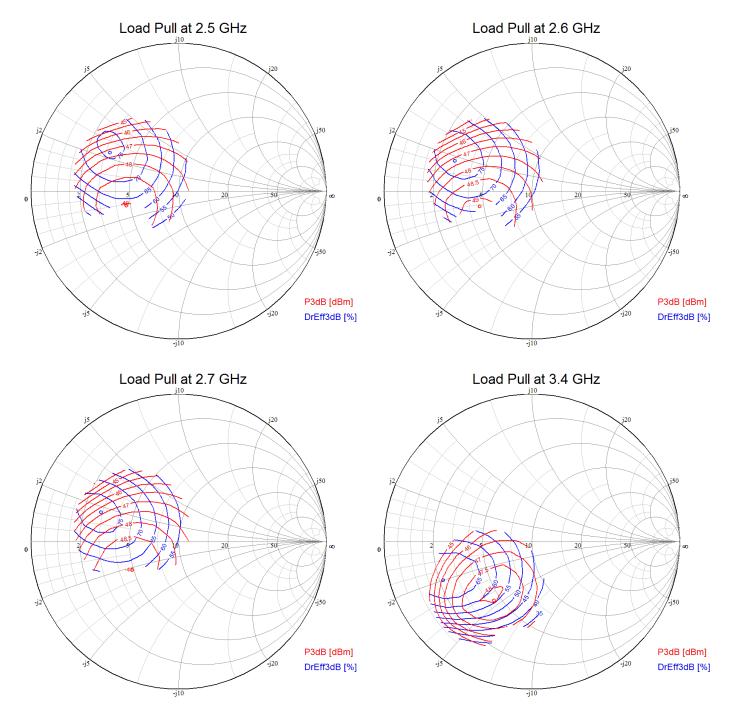
Test conditions unless otherwise noted: V_D = 48 V, I_{CQ} = 131 mA, T = 25°C, Pulsed CW (10% duty cycle, 100 μs width)





Load Pull Plots

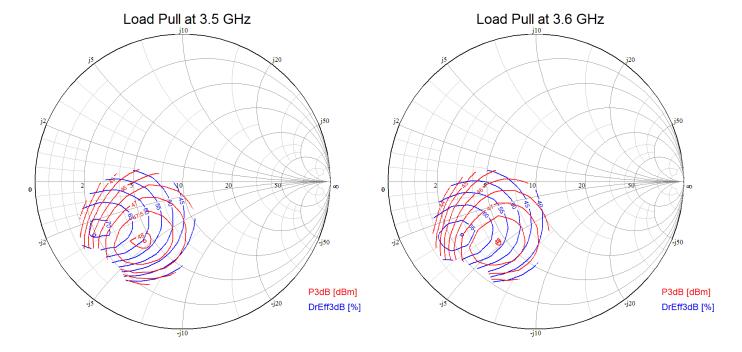
Test conditions unless otherwise noted: $V_D = 48 \text{ V}$, $I_{CQ} = 131 \text{ mA}$, $T = 25^{\circ}\text{C}$, Pulsed CW (10% duty cycle, 100 μ s width)





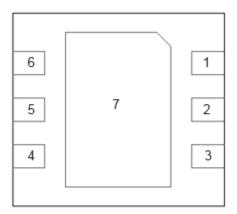
Load Pull Plots

Test conditions unless otherwise noted: $V_D = 48 \text{ V}$, $I_{CQ} = 131 \text{ mA}$, $T = 25^{\circ}\text{C}$, Pulsed CW (10% duty cycle, 100 μ s width)





Pin Configuration and Description



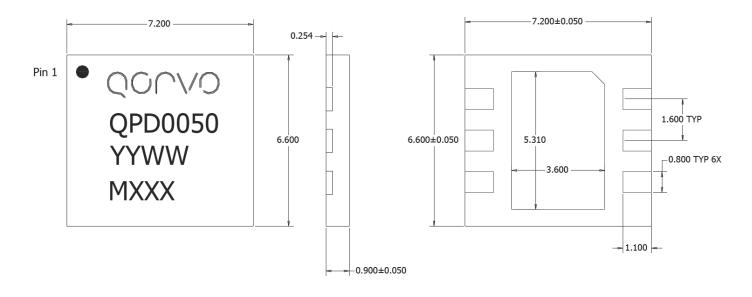
BOTTOM VIEW

Pin No.	Label	Description
1, 2, 3	RF IN, V _G	RF Input, Gate Bias
4, 5, 6	RF OUT, V _D	RF Output, Drain Bias
7 (Backside Paddle)	RF/DC GND	RF/DC Ground



Package Marking and Dimensions

Marking: Product Name – QPD0050 Year, Work Week Assembly Code – YYWW Assembly Number – MXXX



Package Top VIEW

SIDE VIEW

Package BOTTOM VIEW

Notes:

- 1. All dimensions are in mm. Angles are in degrees.
- 2. Exposed metallization is NiAu plated.

Product Compliance Information

ESD Sensitivity Ratings



Caution! ESD-Sensitive Device

ESD Class: TBD Volt. Range: TBD

Test: Human Body Model (HBM) Standard: JEDEC Standard JS-001-2012

ESD Class: TBD Range: TBD

Test: Charged Device Model (CDM) Standard: JEDEC Standard JESD22-C101F

MSL Rating

MSL Rating: Level 3

Test: 260 °C convection reflow

Standard: JEDEC Standard IPC/JEDEC J-STD-020

Solderability

Compatible with both lead-free (260 °C maximum reflow temperature) and tin/lead (245 °C maximum reflow temperature) soldering processes.

Contact plating: NiAu

RoHS Compliance

This part is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- · Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

ECCN

US Department of Commerce EAR99

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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Email: customer.support@qorvo.com

For information about the merger of RFMD and TriQuint as Qorvo: Web: www.gorvo.com

For technical questions and application information: **Email:** btsapplications@tgs.com

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